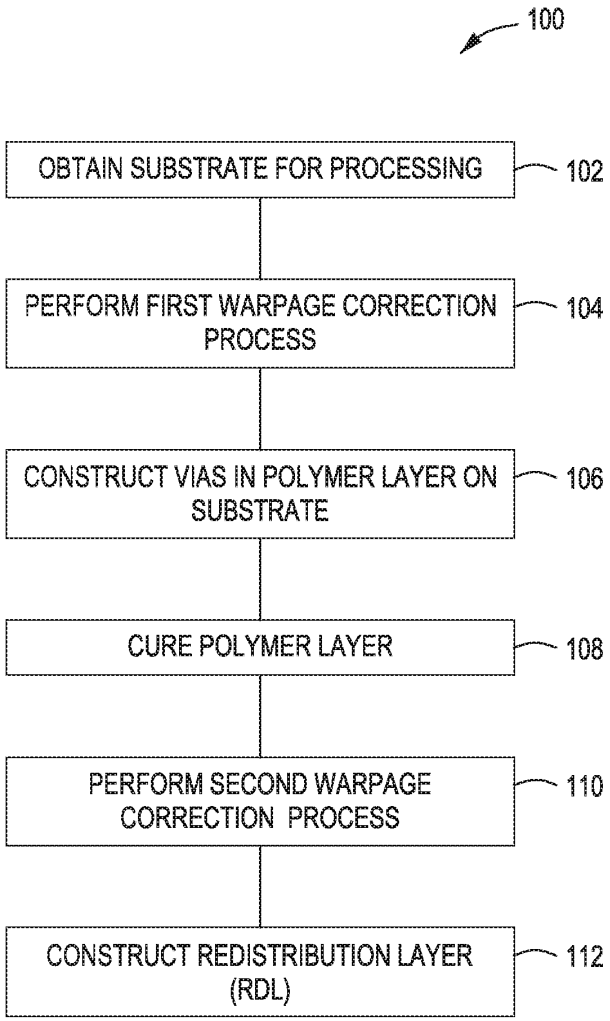

100
OBTAIN SUBSTRATE FOR PROCESSING
102
PERFORM FIRST WARPAGE CORRECTION PROCESS
104
CONSTRUCT VIAS IN POLYMER LAYER ON SUBSTRATE
106
CURE POLYMER LAYER
108
PERFORM SECOND WARPAGE CORRECTION PROCESS
110
CONSTRUCT REDISTRIBUTION LAYER (RDL)
112

FIG. 1

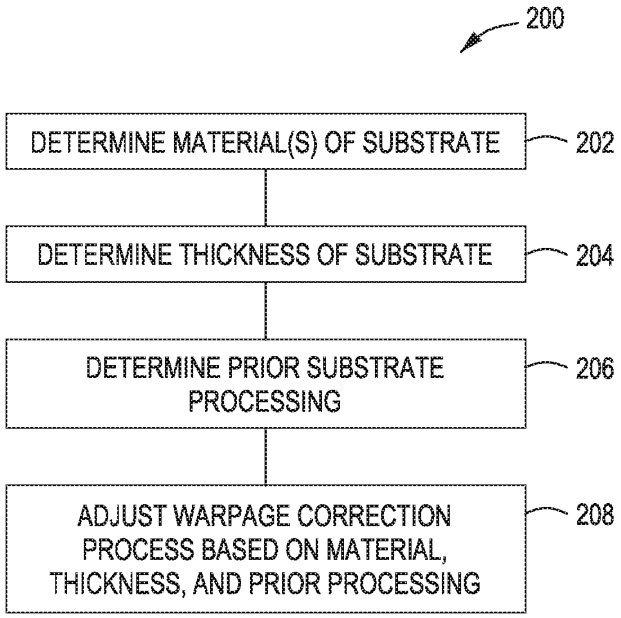

200
DETERMINE MATERIAL(S) OF SUBSTRATE
202
DETERMINE THICKNESS OF SUBSTRATE
204
DETERMINE PRIOR SUBSTRATE PROCESSING
206
ADJUST WARPAGE CORRECTION PROCESS BASED ON MATERIAL, THICKNESS, AND PRIOR PROCESSING
208

FIG. 2

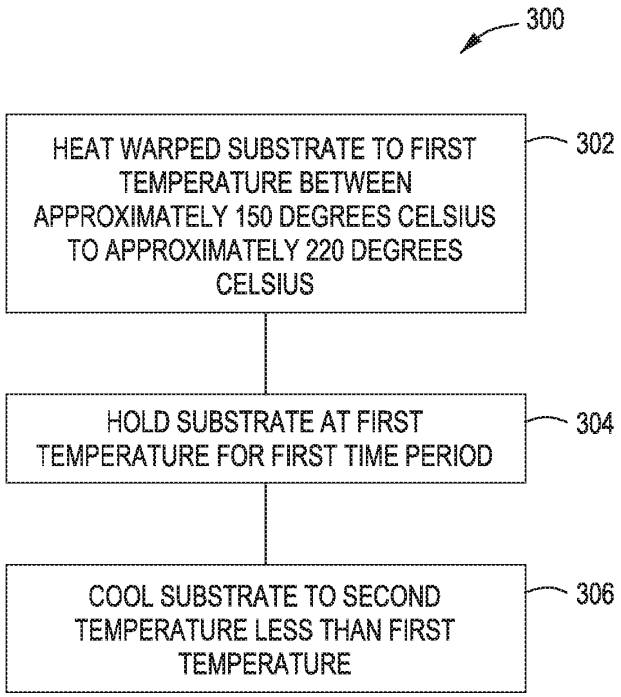

300
HEAT WARPED SUBSTRATE TO FIRST TEMPERATURE BETWEEN APPROXIMATELY 150 DEGREES CELSIUS TO APPROXIMATELY 220 DEGREES CELSIUS
302
HOLD SUBSTRATE AT FIRST TEMPERATURE FOR FIRST TIME PERIOD
304
COOL SUBSTRATE TO SECOND TEMPERATURE LESS THAN FIRST TEMPERATURE
306

FIG. 3

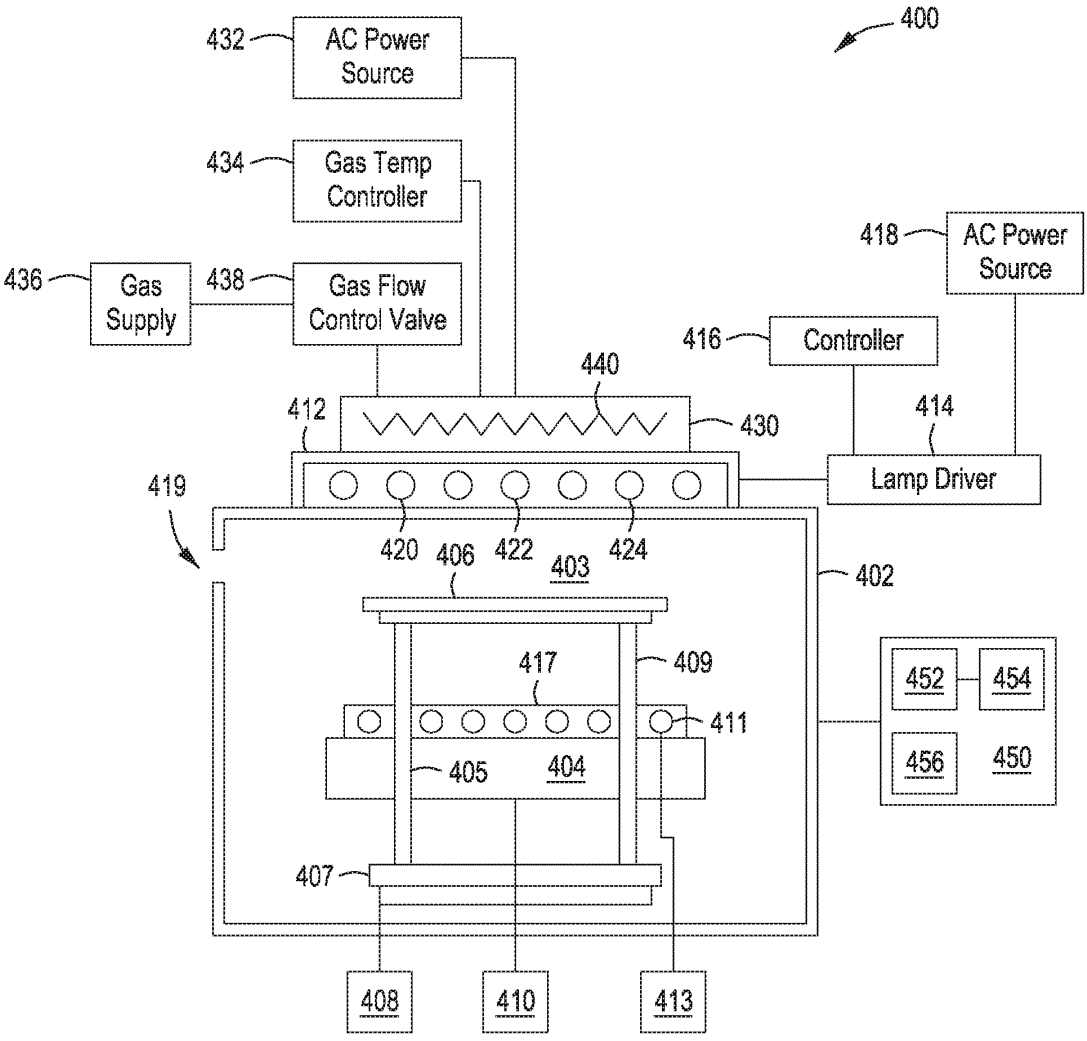

400
432
AC Power Source
434
Gas Temp Controller
436
Gas Supply
438
Gas Flow Control Valve
418
AC Power Source
416
Controller
414
Lamp Driver
440
412
430
419
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402
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413

FIG. 4